



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



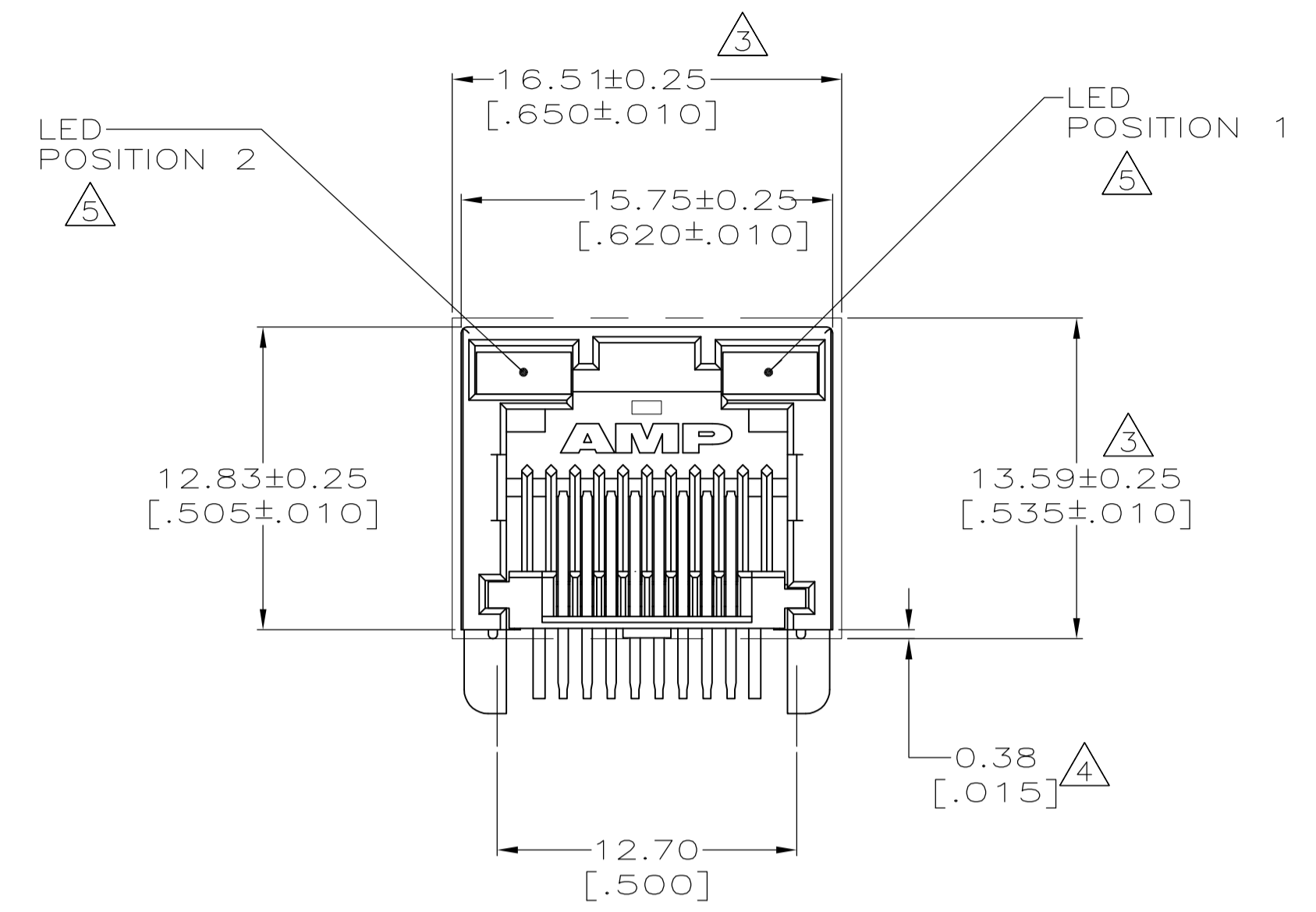
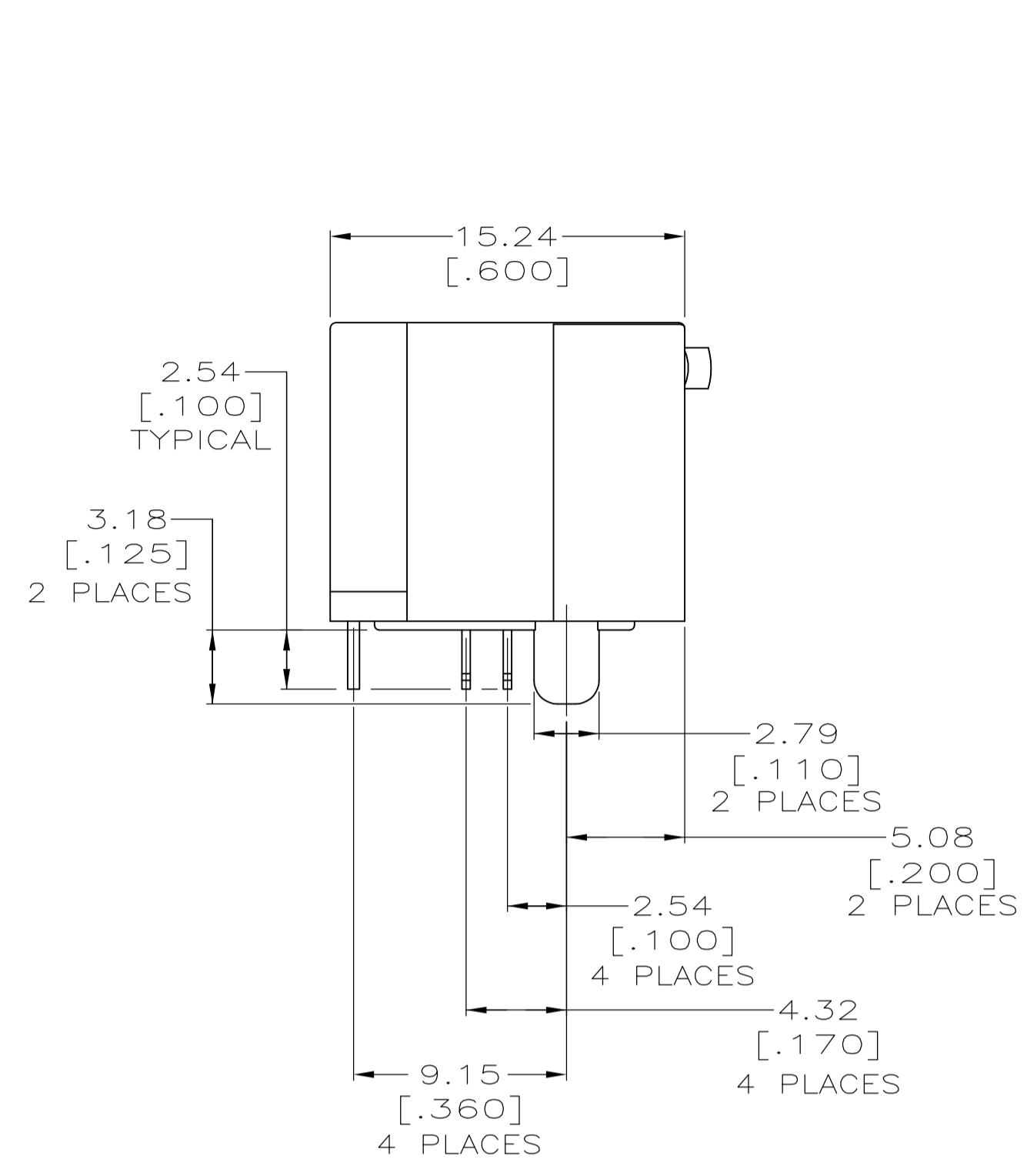
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

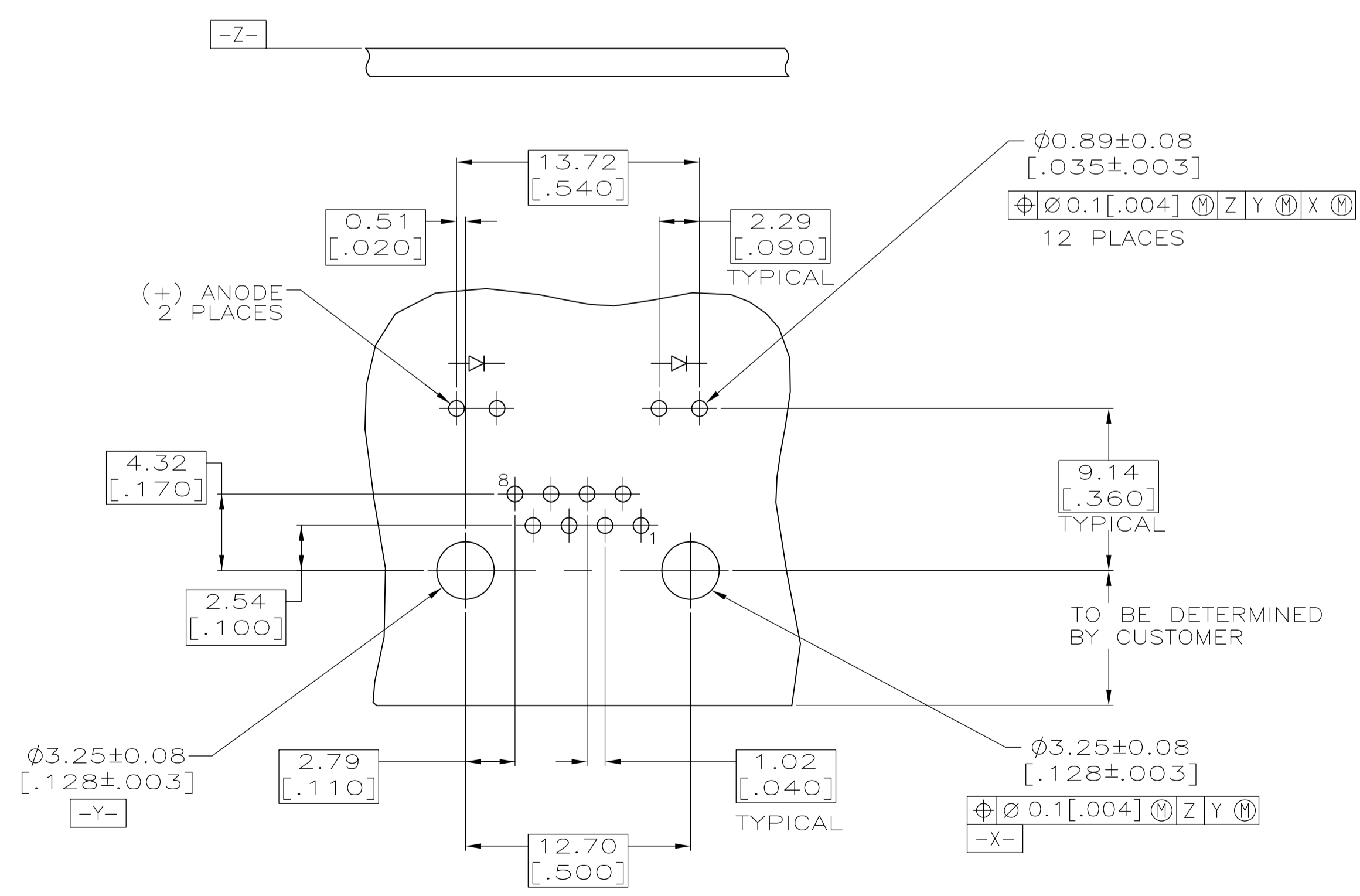
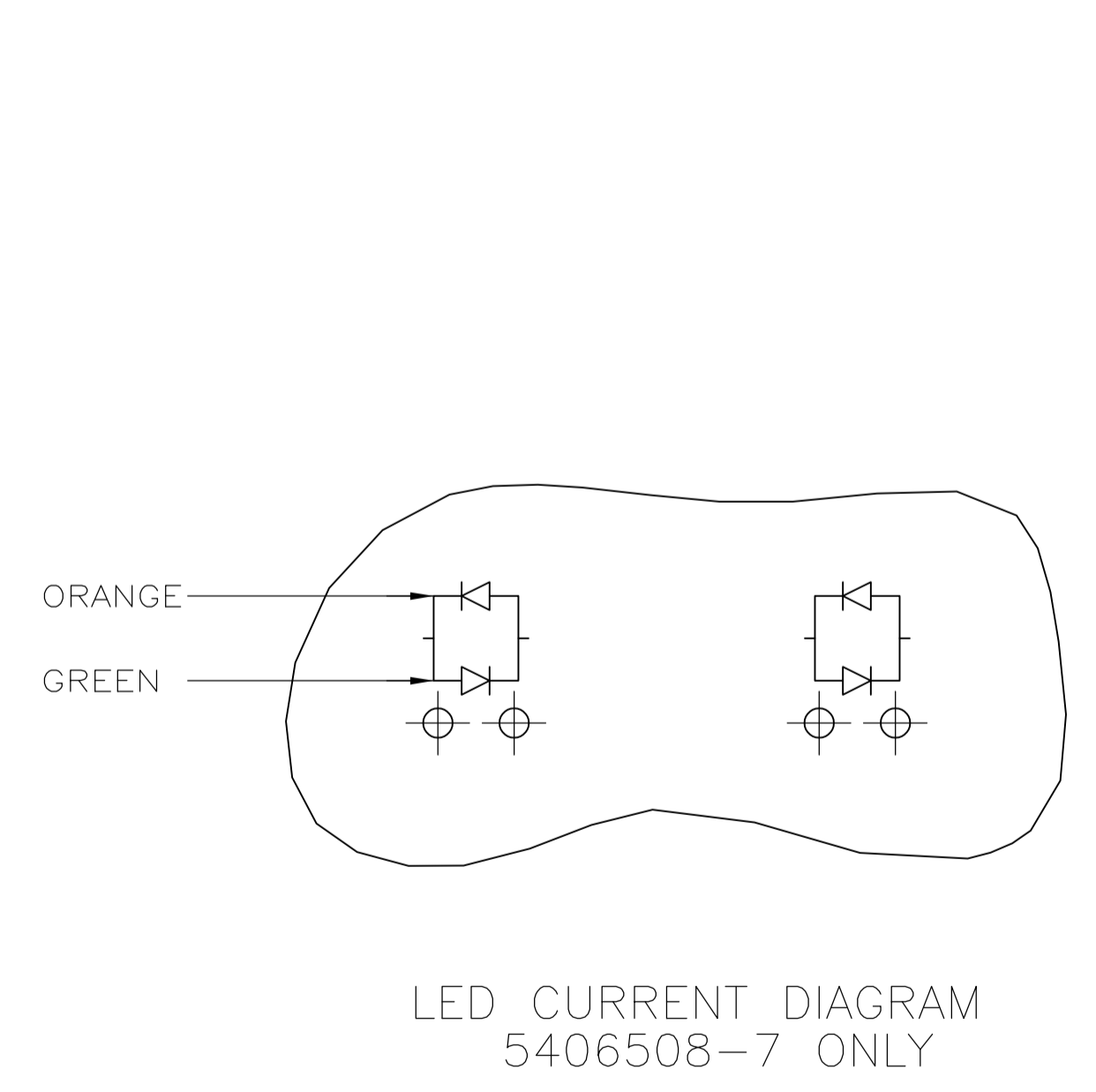
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





- MATERIAL:**  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.**
- SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.**
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.**
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- OBsolete PARTS: OBsolete CIS STREAMLINING PER D.RENAUD/D.SINISI**



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

OBsolete	ORANGE/GREEN	ORANGE/GREEN	-5406508-7
	YELLOW	YELLOW	-5406508-6
	GREEN	YELLOW	5406508-4
OBsolete	YELLOW	-	-5406508-3
	-	GREEN	-5406508-2
	YELLOW	GREEN	-5406508-1
POSITION 2		POSITION 1	PART NUMBER
INDICATOR COLOR			

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	J. ALCORTA - DOCK 5	10JUN2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm [INCHES]		CIK	J. WESTMAN	10JUN2005	Tyco Electronics	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER	10JUN2005	NAME	
0. PLC	± -	PRODUCT SPEC				
1. PLC	± -	108-1163-4				
2. PLC	± 0.25[.01]	APPLICATION SPEC				
3. PLC	± 0.13[.005]	114-2154				
4. PLC	± -	WEIGHT				
ANGLES	± -	A1 00779 C=5406508				
MATERIAL	FINISH	CUSTOMER DRAWING				
		SCALE	1:1	SHEET	1 OF 1	REV
		A1				